

Press Release

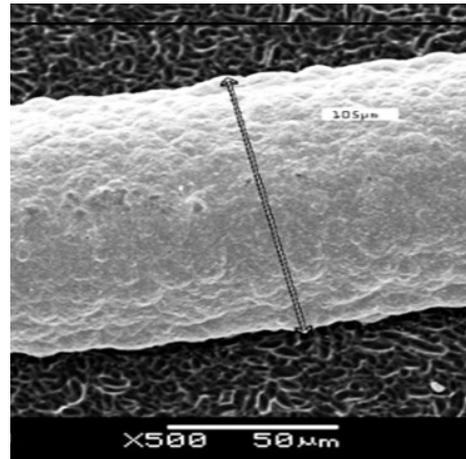
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For immediate release

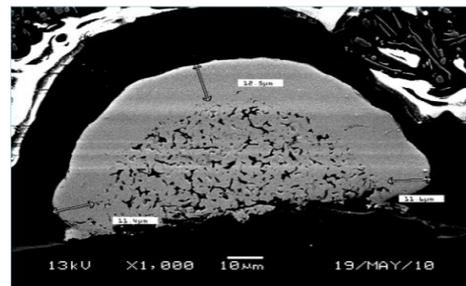
Technic Releases Higher Efficiency Reduced Silver Process

Cranston, Rhode Island, USA – Technic is pleased to announce the release of TechniSol[®] Ag 2460, a cyanide free silver plating solution formulated specifically for use with RSP (Reduced Silver Paste) Technology on silicon solar cells. RSP Technology applies a fine line screen printed seed layer that is then electroplated with a smooth silver layer, resulting in increased efficiencies at a significantly reduced cost. The bath operates at 20 g/l silver, a concentration similar to most other baths in the industry, but because of key advances in its formulation TechniSol[®] Ag 2460 produces very fine grain deposits with no lateral growth. This improved electrolyte formulation also allows manufacturers to plate up to 30% faster and still maintain optimum deposit integrity.

In addition to the advantages in RSP Technology, TechniSol[®] Ag 2460 may be used to plate on nickel or copper grid lines, creating a superior solderable layer. TechniSol[®] Ag 2460 is also formulated for compatibility with LIP (Light Induced Plating) as well as standard electroplating applications.



Top view: TechniSol[®] Ag 2460 x500



Cross section: TechniSol[®] Ag 2460

“RSP Technology can reduce front side metallization costs up to 50% while also improving cell efficiency. TechniSol[®] Ag 2460 maximizes these efficiency gains and improves cell through-put, which establishes it as a leading silver plating solution in the solar industry.”

- *Anthony Gallegos*
Technic Global Product Manager for Solar Technology

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For information on Technic and Technic products go to: www.technic.com or contact Technic at (401) 781-6100